

# **Notice of References Cited**

Application/Control No.  
**09/430,350**

Applicant(s)/Patent Under Reexam  
**Sutera et al.**

Examiner  
**Hugh Jones**

Art Unit  
**2123**

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## **U.S. PATENT DOCUMENTS**

	Document Number Country Code-Number-Kind Code	Date MM-YYYY <sup>1</sup>	Name	Classification <sup>2</sup>	
A	6,405,350	6/2002	Tawada	716	5
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	Document Number Country Code-Number-Kind Code	Date MM-YYYY <sup>1</sup>	Country	Name	Classification <sup>2</sup>	
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O						
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R						
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T						

## **NON-PATENT DOCUMENTS**

	Include, as applicable: Author, Title, Date, Publisher, Edition or Volume, Pertinent Pages
U	Yang et al.; Deep submicron on-chip crosstalk; IEEE Proc. 16th Inst. Meas. Tech. Conf.; pp. 1788-1793; 5/1999.
V	Davis et al.; Length, scaling, and material dependence of crosstalk between distributed RC Interconnects; IEEE Int. Conf. Interconnect Tech.; pp. 227-229; 5/1999.
W	Oh et al.; A scaling scheme and optimization methodology for deep sub-micron interconnect; IEEE Int. Conf. Computer Design; pp. 320-325; 10/1996.
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\* A copy of this reference is not being furnished with this Office action. See MPEP § 707.05(a).

<sup>1</sup> Dates in MM-YYYY format are publication dates.

<sup>2</sup> Classifications may be U.S. or foreign.